

ABSTRACT

To provide a workpiece processing method capable of reducing TTV of a workpiece. A workpiece processing method comprises: a step for adhering a surface protective sheet to a surface of a workpiece having a front surface and a rear surface; and a step for grinding the rear surface of the workpiece with the surface protective sheet adhered thereto, wherein the surface of the workpiece has a bump electrode, in the step for adhering the surface protective sheet, a projecting pattern is formed in a region different from a region at an outer periphery of the surface of the workpiece where the bump electrode is formed, the surface protective sheet is adhered to bury the bump electrode, and H_b and H_1 , where H_b is a height of the bump electrode and H_1 is a height of the projecting pattern, satisfy the relationship $H_b/8 < H_1 < H_b/1.5$.

(Fig. 2B)